

# **Product Change Notification / JAON-17DZYV010**

Date:											
01-Oct-2021											
<b>Product Category:</b>	Product Category:										
Memory											
PCN Type:											
Manufacturing Change											
Notification Subject	t:										
CCB 4560 Final Notice: Qualification of SIGN as a new assembly site for selected SST39LF80xx, SST39VF160xx and SST39VF80xx device families available in 48L TSOP (12x20mm) package.											
Affected CPNs:											
	cted_CPN_10012021.pdf cted_CPN_10012021.csv										
Notification Text:											
PCN Status:Final Notification											
PCN Type:Manufacturing Change											
<b>Microchip Parts Affected:</b> Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)											
<b>Description of Change:</b> Qualification of SIGN as a new assembly site for selected SST39LF80xx, SST39VF160xx and SST39VF80xx device families available in 48L TSOP (12x20mm) package.											
Pre and Post Change Summary:											
	Pre Change	Post Change									

Assembly Site	Lingsen Precisior (Li	n Industries, LTD. PI)	Signetics Corporation (SIGN)					
Bond Wire material	А	u	Au					
Die Attach material	83	40	AP-4	1300				
Mold compound material	G7	00	G700					
Lead frame material	C70	)25	C7025					
DAP Surface plating	Ring /Selec	tive Plating	Ring /Selective Plating					
Lead frame paddle size	207x142mils Note 1	160x130mils Note 2	209x165mils Note 1	159x165mils Note 2				
	See a	ittached pre and p	ost change comparison.					

Note 1: Applicable for SST39VF160xx device family.

Note 2: Applicable for SST39LF80xx and SST39VF80xx device families

# Impacts to Data Sheet:None

## Change ImpactNone

**Reason for Change:**To improve on-time delivery performance by qualifying SIGN as a new assembly site.

### **Change Implementation Status:**In Progress

Estimated First Ship Date:October 31, 2021 (date code: 2145)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

### **Time Table Summary:**

	February 2021					^	October 2021					
Workweek	0	0	0	0	1		4	4	4	4	4	4
	6	7	8	9	0		0	1	2	3	4	5
Initial PCN Issue				v								
Date				Х								

Qual Report Availability				Х			
Final PCN Issue Date				Х			
Estimated Implementation Date							Х

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**February 19, 2021: Issued initial notification.

April 08, 2021: Re-issued initial notification to update the pre and post comparison table to modify SIGN die attach material from 8340 to AP-4300. Updated LPI DAP surface plating from Ring plating to Ring /Selective plating and updated SIGN DAP surface plating from Double ring plating to Ring /Selective plating. Updated the Qual plan summary to modify SIGN die attach material from 8340 to AP-4300 and to modify SIGN DAP surface plating from Double ring plating to Ring /Selective plating.

October 1, 2021: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

### Attachments:

PCN\_JAON-17DZYV010\_Qual Report.pdf PCN\_JAON-17DZYV010\_Pre and Post Change\_Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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### Affected Catalog Part Numbers (CPN)

SST39VF1601C-70-4C-EKE

SST39VF1602C-70-4C-EKE

SST39VF1601C-70-4I-EKE

SST39VF1602C-70-4I-EKE

SST39VF1602C-70-4I-EKE-MCK

SST39VF1601C-70-4C-EKE-T

SST39VF1602C-70-4C-EKE-T

SST39VF1601C-70-4I-EKE-T

SST39VF1602C-70-4I-EKE-T

SST39LF801C-55-4C-EKE

SST39LF802C-55-4C-EKE

SST39VF801C-70-4C-EKE

SST39VF802C-70-4C-EKE

SST39VF801C-70-4I-EKE

SST39VF802C-70-4I-EKE

SST39LF801C-55-4C-EKE-T

SST39LF802C-55-4C-EKE-T

SST39VF801C-70-4C-EKE-T

SST39VF802C-70-4C-EKE-T

SST39VF801C-70-4I-EKE-T

SST39VF802C-70-4I-EKE-T

Date: Friday, October 01, 2021